

ADC12D1600/1000RF

ADVANCE INFORMATION

July 1, 2011

12-Bit, 3.2/2.0 GSPS Ultra High-Speed ADC

1.0 General Description

The 12-bit 1.6/1.0 GSPS ADC12D1600/1000RF is an RF-sampling GSPS ADC that can directly sample input frequencies up to and above 2.7 GHz. The ADC12D1600/1000RF augments the very large Nyquist zone of National's GSPS ADCs with excellent noise and linearity performance at RF frequencies, extending its usable range beyond the 5th Nyquist zone

The ADC12D1600/1000RF provides a flexible LVDS interface which has multiple SPI programmable options to facilitate board design and FPGA/ASIC data capture. The LVDS outputs are compatible with IEEE 1596.3-1996 and supports programmable common mode voltage. The product is packaged in a lead-free 292-ball thermally enhanced BGA package over the rated industrial temperature range of -40°C to +85°C.

2.0 Features

- Excellent noise and linearity up to and above f_{IN} = 2.7 GHz
- Configurable to either 3.2/1.6 GSPS interleaved or 1600/1000 MSPS dual ADC
- New DESCLKIQ Mode for high bandwidth, high sampling rate apps
- Pin-compatible with ADC1xD1x00, ADC12Dx00RF
- AutoSync feature for multi-chip synchronization
- Internally terminated, buffered, differential analog inputs
- Interleaved timing automatic and manual skew adjust
- Test patterns at output for system debug
- Time Stamp feature to capture external trigger
- \blacksquare Programmable gain, offset, and t_{AD} adjust feature
- 1:1 non-demuxed or 1:2 demuxed LVDS outputs

3.0 Applications

- 3G/4G Wireless Basestation
 - Receive Path
 - DPD Path
- Wideband Microwave Backhaul
- RF Sampling Software Defined Radio
- Military Communications
- SIGINT
- RADAR / LIDAR
- Wideband Communications
- Consumer RF
- Test and Measurement

4.0 Key Specifications

■ Resolution 12 Bits

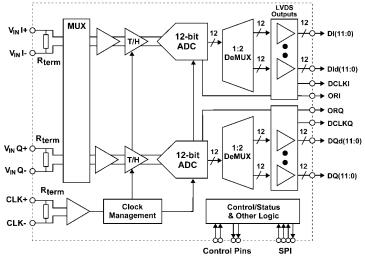
Interleaved 3.2/2.0 GSPS ADC

- IMD₃ (Fin = 2.7GHz @ -13dBFS)
 IMD₃ (Fin = 2.7GHz @ -16dBFS)
 -70/-69 dBc (typ)
- Noise Floor -154.6/-154.0 dBm/Hz (typ)
- Noise Power Ratio TBD/TBD dB (typ)
- Power 3.99/3.51W (typ)

Dual 1600/1000 MSPS ADC, Fin = 498 MHz

- ENOB 9.3/9.4 Bits (typ)
 SNR 58.4/58.8 dB (typ)
- SFDR 68.8/71.9 dBc (typ)
- Power per Channel 1.99/1.75W (typ)

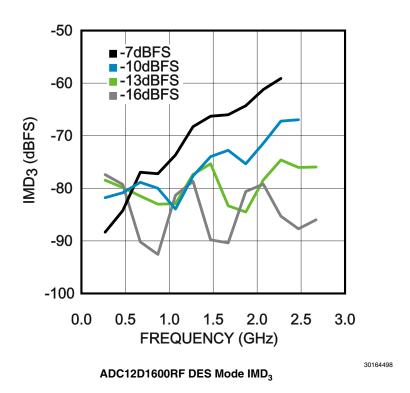
5.0 Block Diagram



Simplified Block Diagram

30164411

6.0 RF Performance



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7.0 Connection Diagram

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	
A	GND	V_A	SDO	ТРМ	NDM	V_A	GND	V_E	GND_E	Dld0+	V_DR	Dld3+	GND_DR	DId6+	V_DR	DId9+	GND_DR	Dld11+	Dld11-	GND_DR	A
В	Vbg	GND	ECEb	SDI	CalRun	V_A	GND	GND_E	V_E	Dld0-	Dld2+	Dld3-	Dld5+	DId6-	Dld8+	DId9-	Dld10+	DI0+	DI1+	DI1-	В
С	Rtrim+	Vcmo	Rext+	SCSb	SCLK	V_A	NC	V_E	GND_E	Dld1+	Dld2-	Dld4+	DId5-	Dld7+	Dld8-	Dld10-	DI0-	V_DR	DI2+	DI2-	С
D	DNC	Rtrim-	Rext-	GND	GND	CAL	DNC	V_A	V_A	Dld1-	V_DR	DId4-	GND_DR	Dld7-	V_DR	GND_DR	V_DR	DI3+	DI4+	DI4-	D
E	V_A	Tdiode+	DNC	GND													GND_DR	DI3-	DI5+	DI5-	E
F	V_A	GND_TC	Tdiode-	DNC													GND_DR	DI6+	DI6-	GND_DR	F
G	v_тс	GND_TC	v_тс	v_тс										_			DI7+	DI7-	DI8+	DI8-	G
н	Vinl+	v_тс	GND_TC	V_A				GND	GND	GND	GND	GND	GND				DI9+	DI9-	DI10+	DI10-	н
J	Vinl-	GND_TC	v_тс	Vbiasl				GND	GND	GND	GND	GND	GND				V_DR	DI11+	DI11-	V_DR	J
κ	GND	Vbiasl	v_тс	GND_TC				GND	GND	GND	GND	GND	GND				ORI+	ORI-	DCLKI+	DCLKI-	κ
L	GND	VbiasQ	v_тс	GND_TC				GND	GND	GND	GND	GND	GND				ORQ+	ORQ-	DCLKQ+	DCLKQ-	L
М	VinQ-	GND_TC	v_тс	VbiasQ				GND	GND	GND	GND	GND	GND				GND_DR	DQ11+	DQ11-	GND_DR	М
N	VinQ+	v_тс	GND_TC	V_A				GND	GND	GND	GND	GND	GND				DQ9+	DQ9-	DQ10+	DQ10-	N
Р	v_тс	GND_TC	v_тс	v_тс													DQ7+	DQ7-	DQ8+	DQ8-	P
R	V_A	GND_TC	v_тс	v_тс													V_DR	DQ6+	DQ6-	V_DR	R
т	V_A	GND_TC	GND_TC	GND													V_DR	DQ3-	DQ5+	DQ5-	Т
U	GND_TC	CLK+	PDI	GND	GND	RCOut1-	DNC	V_A	V_A	DQd1-	V_DR	DQd4-	GND_DR	DQd7-	V_DR	V_DR	GND_DR	DQ3+	DQ4+	DQ4-	U
V	CLK-	DCLK _RST+	PDQ	CalDly	DES	RCOut2+	RCOut2-	V_E	GND_E	DQd1+	DQd2-	DQd4+	DQd5-	DQd7+	DQd8-	DQd10-	DQ0-	GND_DR	DQ2+	DQ2-	V
w	DCLK _RST-	GND	DNC	DDRPh	RCLK-	V_A	GND	GND_E	V_E	DQd0-	DQd2+	DQd3-	DQd5+	DQd6-	DQd8+	DQd9-	DQd10+	DQ0+	DQ1+	DQ1-	w
Y	GND	V_A	FSR	RCLK+	RCOut1+	V_A	GND	V_E	GND_E	DQd0+	V_DR	DQd3+	GND_DR	DQd6+	V_DR	DQd9+	GND_DR	DQd11+	DQd11-	GND_DR	Y
	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	
																				3016	4401

FIGURE 1. ADC12D1600/1000RF Connection Diagram

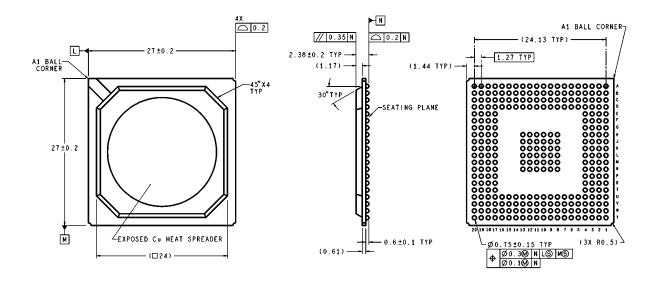
The center ground pins are for thermal dissipation and must be soldered to a ground plane to ensure rated performance.

8.0 Ordering Information

Industrial Temperature Range (-40°C < T _A < +85°C)	NS Package					
ADC12D1600/1000RFIUT/NOPB	Lead-free 292-Ball BGA Thermally Enhanced Package					
ADC12D1600RFRB	Reference Board					

If Military/Aerospace specified devices are required, please contract the National Semiconductor Sales Office/Distributors for availability and specifications. IBIS models are available at: http://www.national.com/analog/adc/ibis_models.

9.0 Physical Dimensions inches (millimeters) unless otherwise noted



DIMENSIONS ARE IN MILLIMETERS

UFH292A (Rev A)

NOTES: UNLESS OTHERWISE SPECIFIED REFERENCE JEDEC REGISTRATION MS-034, VARIATION BAL-2.

292-Ball BGA Thermally Enhanced Package Order Number ADC12D1600/1000RFUIT NS Package Number UFH292A

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Notes

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LVDS	www.national.com/lvds	Packaging	www.national.com/packaging				
Power Management	www.national.com/power	Green Compliance	www.national.com/quality/green				
Switching Regulators	www.national.com/switchers	Distributors	www.national.com/contacts				
LDOs	www.national.com/ldo	Quality and Reliability	www.national.com/quality				
LED Lighting	www.national.com/led	Feedback/Support	www.national.com/feedback				
Voltage References	www.national.com/vref	Design Made Easy	www.national.com/easy				
PowerWise® Solutions	www.national.com/powerwise	Applications & Markets	www.national.com/solutions				
Serial Digital Interface (SDI)	www.national.com/sdi	Mil/Aero	www.national.com/milaero				
Temperature Sensors	www.national.com/tempsensors	SolarMagic™	www.national.com/solarmagic				
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